

Please amend the specification as follows:

In the Claims:

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1. (amended) A method and system of wire bonding a semiconductor die to a lead, comprising steps of:

A1

attaching a first end of a first bonding wire to a semiconductor die with a ball bond;

attaching a second end of the first bonding wire to an interposer pad with a stitch bond;

attaching a first end of a second bonding wire to the interposer pad with a ball bond; and

attaching the second end of the second bonding wire to the lead with a stitch bond.

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Please cancel Claim 3 without prejudice.

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8. (amended) A semiconductor device, comprising:

A2

a semiconductor die disposed on a substrate;

a plurality of interposer pads on said substrate;

a plurality of leads on the substrate;

a plurality of bonding wires attached to the semiconductor die with ball bonds and to the leads with stitch bonds, said wires attached to said interposer pads.

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11. (amended) The semiconductor device as recited in Claim 8, wherein each of said bonding wires comprises a bonding wire between the semiconductor die and each interposer pad attached to a bonding pad on the semiconductor die with a ball bond and to said interposer pad with a stitch bond and a bonding wire between the interposer pad and the lead attached to the interposer pad with a ball bond and to each lead with a stitch bond.

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A3